

Customer Training Workshop

Traveo™ II Automotive Cluster 2D Power Supply and Monitoring

Q4 2020



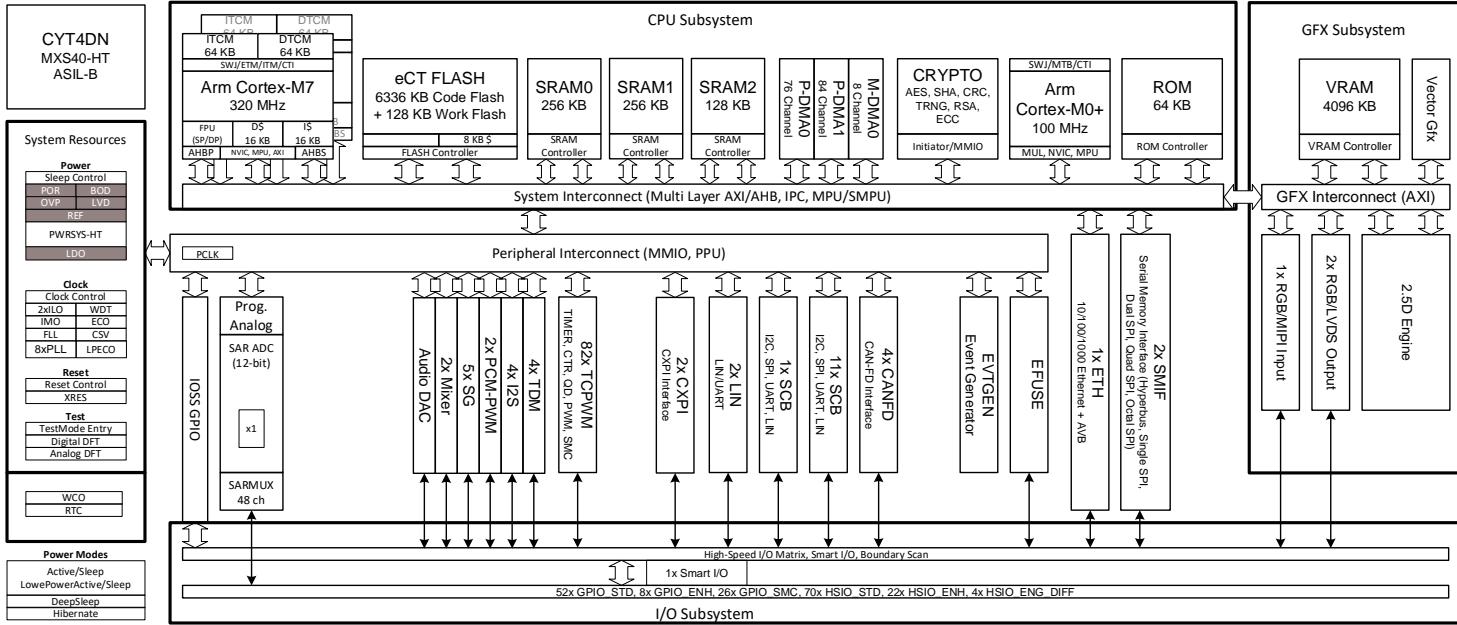
Target Products

- › Target product list for this training material

| Family Category | Series | Code Flash Memory Size |
|-------------------------------|--------|------------------------|
| Traveo™ II Automotive Cluster | CYT3DL | Up to 4160 KB |
| Traveo™ II Automotive Cluster | CYT4DN | Up to 6336 KB |

Introduction

Power supply monitoring functions are in System Resources



Hint Bar

Review TRM section 16.2 for additional details

Power-on reset (POR)

Brownout detection (BOD)

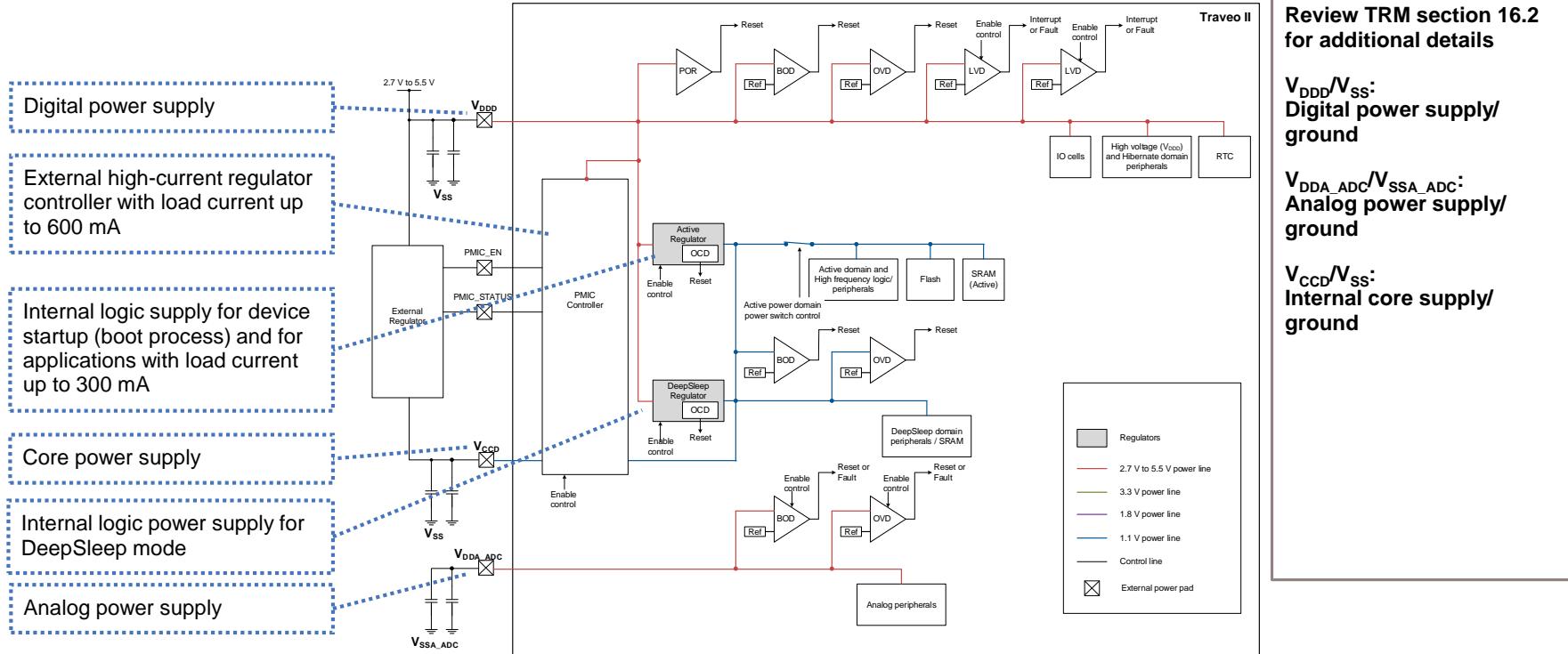
Over-voltage detection (OVD)

Low-voltage detection (LVD)

Low drop-out regulator (LDO)

Power Supply Overview

- › 2.7–5.5-V power supply range
- › Core regulators for High Current, Active, and DeepSleep modes



Power Pins and Rails

› Power/ground pins and voltage range

| Supply Pin | Ground Pin | Power Supply Voltage Range | Description |
|---------------------------|---|----------------------------|------------------------------------|
| V _{DDD} | V _{SS} or V _{SSD} | 2.7 V to 5.5 V | Digital and GPIO supply |
| V _{CCD} | V _{SS} or V _{SSD} | 1.09 V to 1.21 V | Core supply |
| V _{DDIO_SMIF} | V _{SS} | 1.7 V to 2.0 V | HSIO_ENH I/O supply for 1.8-V SMIF |
| V _{DDIO_SMIF_HV} | V _{SS} | 3.0 V to 3.6 V | HSIO_STD I/O supply for 3.3-V SMIF |
| V _{DDIO_HSIO} | V _{SS} or V _{SSIO_HSIO} | 3.0 V to 3.6 V | HSIO_STD I/O supply |
| V _{DDIO_SMC} | V _{SS} or V _{SSIO_SMC} | 2.7 V to 5.5 V | SMC I/O supply |
| V _{DDIO_GPIO} | V _{SS} or V _{SSIO_GPIO} | 2.7 V to 5.5 V | GPIO supply |
| V _{DDHA_FPD0} | V _{SSA_FPD0} | 3.0 V to 3.6 V | FPD-Link0 line drivers supply |
| V _{DDA_FPD0} | V _{SSA_FPD0} | 1.09 V to 1.21 V | FPD-Link0 core supply |
| V _{DDPLL_FPD0} | V _{SSA_FPD0} | 1.09 V to 1.21 V | FPD-Link0 PLL supply |
| V _{DDHA_FPD1} | V _{SSA_FPD1} | 3.0 V to 3.6V | FPD-Link1 line drivers supply |
| V _{DDA_FPD1} | V _{SSA_FPD1} | 1.09 V to 1.21 V | FPD-Link1 core supply |
| V _{DDPLL_FPD1} | V _{SSA_FPD1} | 1.09 V to 1.21 V | FPD-Link1 PLL supply |
| V _{DDA_MIPI} | V _{SSA_MIPI} | 1.09 V to 1.21 V | D-PHY supply |
| V _{DDA_ADC} | V _{SSA_ADC} | 2.7 V to 5.5 V | Analog supply voltage |
| V _{DDA_DAC} | V _{SSA_DAC} | 3.0 V to 3.6 V | Audio DAC supply |

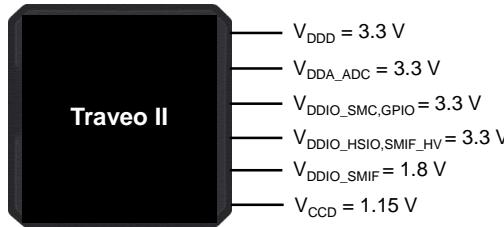
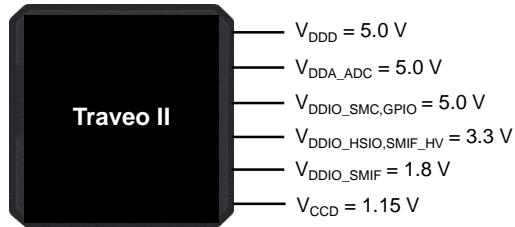
Hint Bar

Review TRM section 16.2.2
for additional details

Power Supply

› Power supply sources

- Multiple analog supply rails and V_{DDIO} rails exist independent of V_{DDD} and V_{CCD}



› Power sequencing requirements

- 1.15-V nominal supplies all need to be shorted, at the same level, and with the same presence

› Advantage

- Less effort and cost because no external power sequencing control is required for applications with load current up to 300 mA

Hint Bar

Review the datasheet

Recommended Operating Conditions

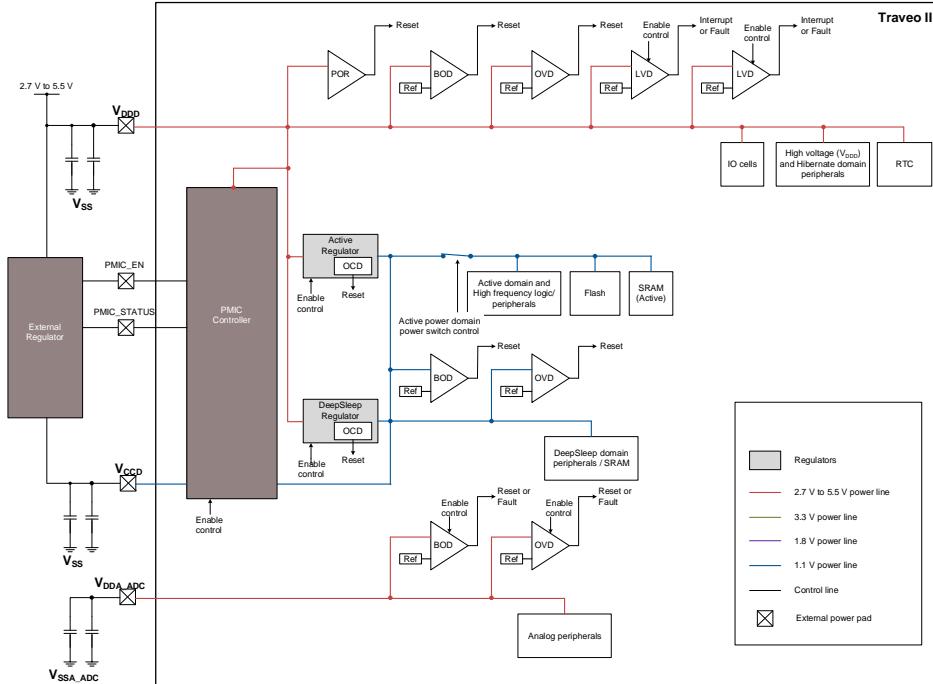
12-Bit SAR ADC DC Specifications when using ADC units

Review TRM sections 16.2.3 and 16.2.4 for additional details

Regulator Selection

PMIC controller selection

- Device starts up with Active regulator, which supports up to 300 mA supply current
- Switches to PMIC controller if supply current of up to 600 mA is required

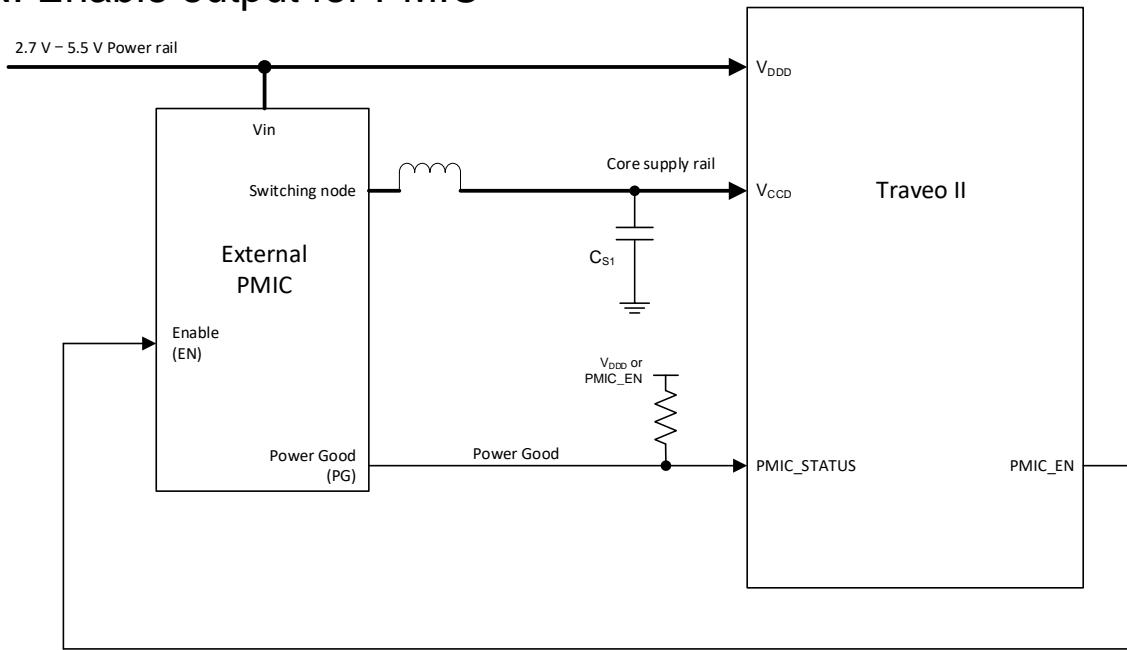


Hint Bar

Review datasheet and TRM section 16.2.5 for additional details

External PMIC Configuration (Hardware)

- › PMIC controller pins
 - PMIC_STATUS: Power Good input from PMIC
 - PMIC_EN: Enable output for PMIC



Hint Bar

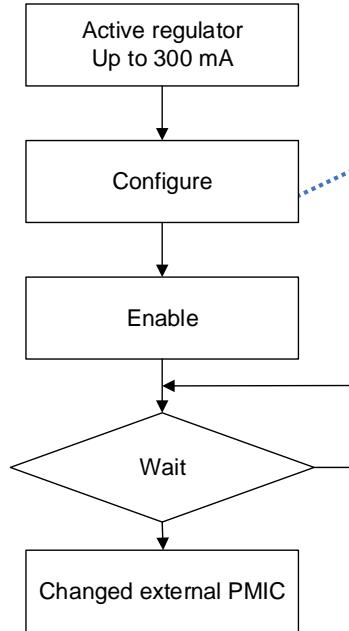
Review datasheet and TRM section 16.2.5 for additional details

Recommended PMICs:
Cypress S6BP501A and
Rohm BD9S200MUF-C

External PMIC Configuration (Software)

› Changing from active regulator to external PMIC

- Setup flow



Call ConfigureRegulator API:

- › PWR_PMIC_CTL.PMIC_STATUS_INEN = 1 to enable the input path for PMIC status
- › PWR_PMIC_CTL.PMIC_STATUS_POLARITY to the setting that indicates an error condition (depending on the polarity of the PMIC status output)
- › PWR_PMIC_CTL.PMIC_CTL_OUTEN = 1 and PWR_PMIC_CTL.PMIC_CTL_POLARITY to the setting that enables the PMIC (depending on polarity of PMIC enable input)
- › PWR_PMIC_CTL.PMIC_CONFIGURED = 1

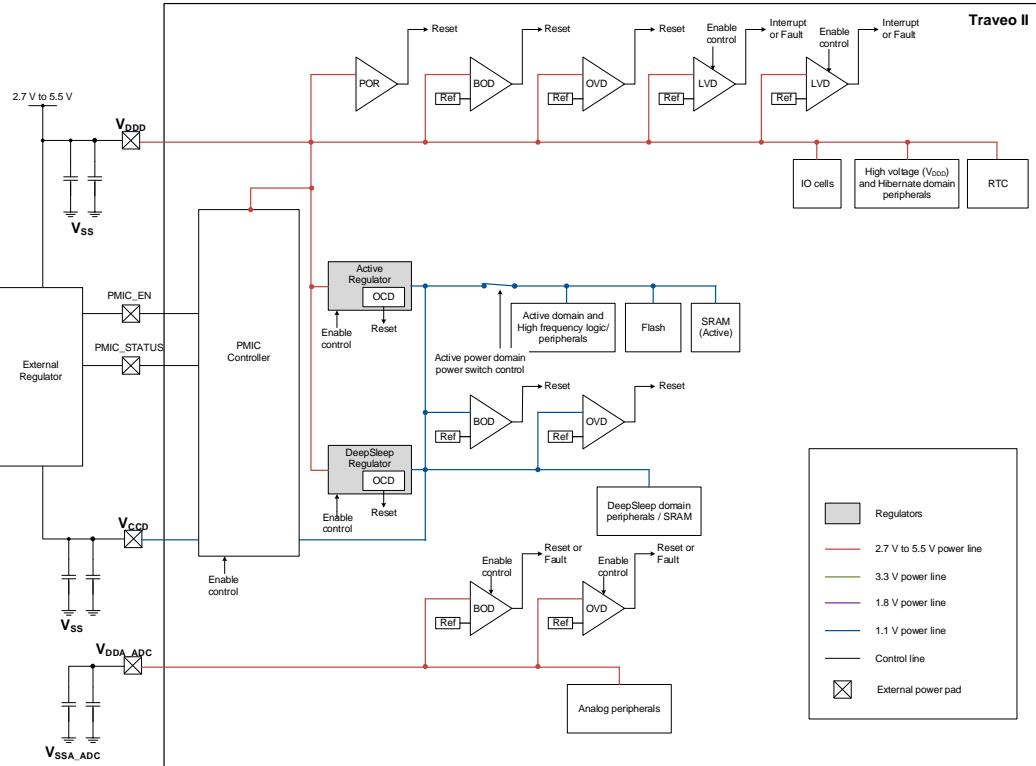
Call SwitchOverRegulators API:

- › PWR_PMIC_CTL2.PMIC_EN = 1
- › Wait until PWR_PMIC_STATUS.SEQ_BUSY = 0 and PWR_PMIC_STATUS.PMIC_ENABLED = 1

This delay depends strongly on the startup time of the PMIC, based on its status output and the value in PWR_PMIC_CTL.PMIC_STATUS_WAIT

Voltage Monitoring Overview

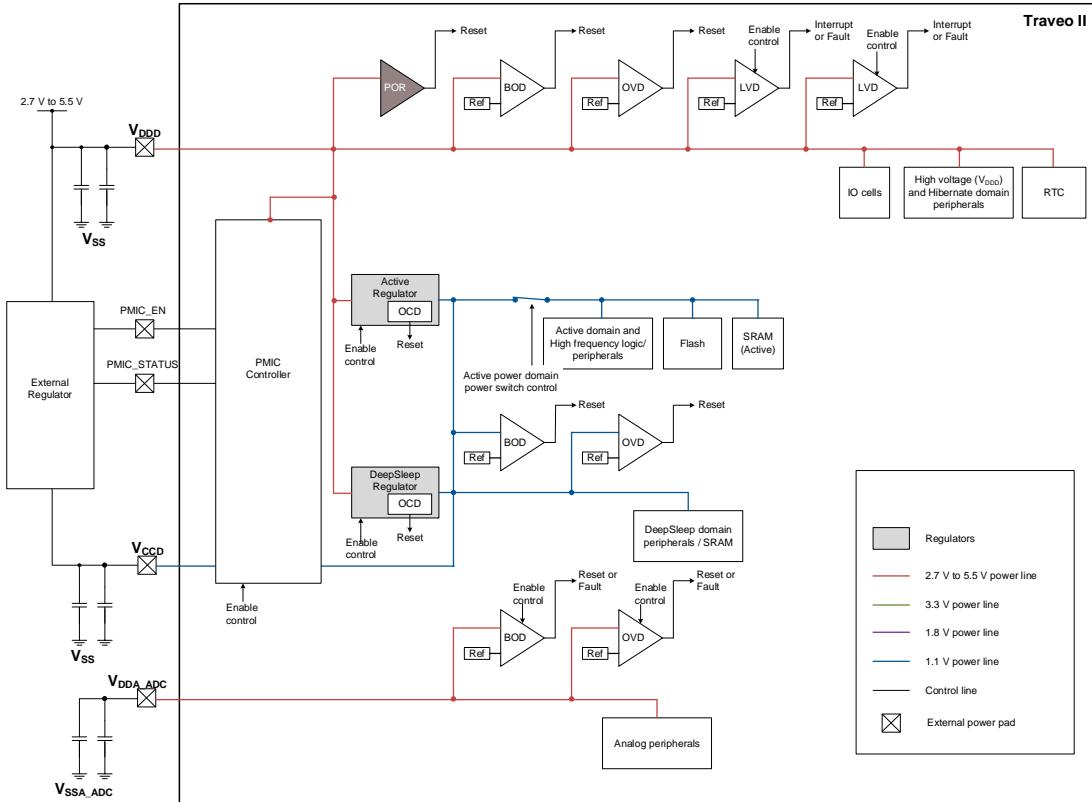
- Supports multiple voltage monitoring features and supply failure protection



Hint Bar

Review datasheet and TRM section 16.3 for additional details

Power-on Reset (POR) Block Diagram

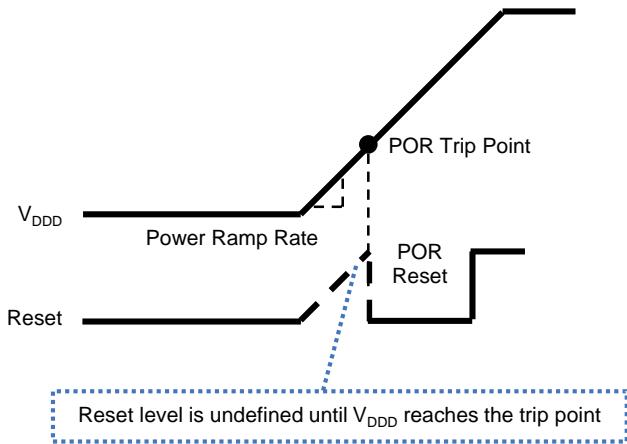


Hint Bar

Review datasheet and TRM section 16.3 for additional details

POR Features

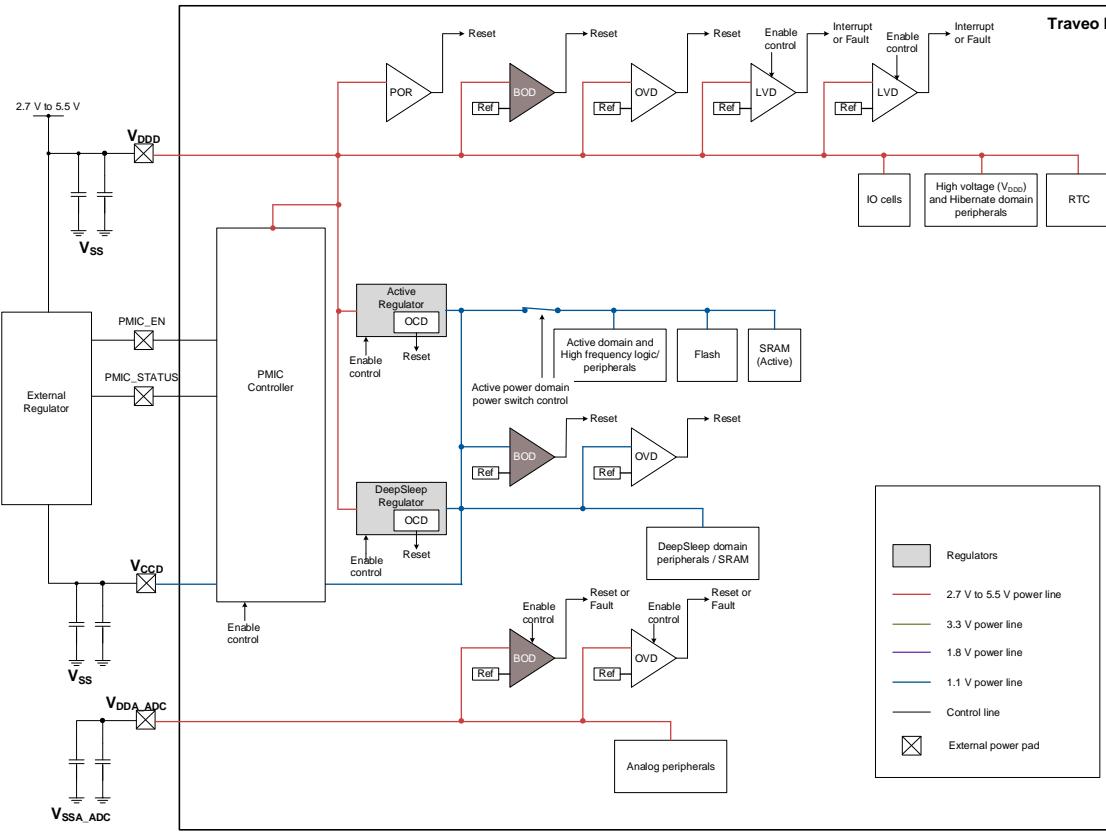
- › Initializes the device at power-up
- › Always on
 - POR on V_{DDD}
 - Provides a reset pulse during the initial power ramp



Hint Bar

Review datasheet and TRM section 16.3.1 for additional details

Brown-out Detection (BOD) Block Diagram



Hint Bar

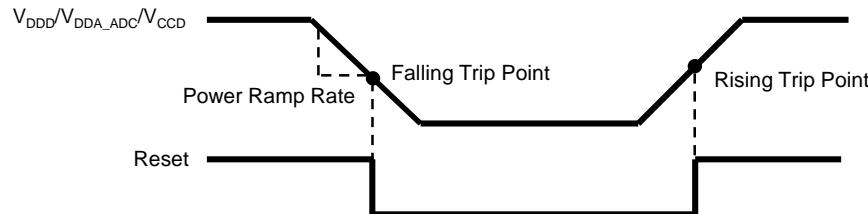
Review datasheet and TRM section 16.3 for additional details

BOD Features

- › Detects supply condition below a threshold and applies a reset to the device
- › Always on except in Hibernate and XRES modes
 - BOD on V_{DDD}
 - Generates a reset if a voltage excursion dips below the falling trip point
 - Supports two trip points: < 2.7 V¹ (default) or < 3.0 V
 - BOD on V_{DDA_ADC}
 - Generates a reset, a fault, or no action² (default) if a voltage excursion dips below the falling trip point
 - Supports two trip points: < 2.7 V¹ (default) or < 3.0 V
 - BOD on V_{CCD}
 - Generates a reset if a voltage excursion dips below the falling trip point

Hint Bar

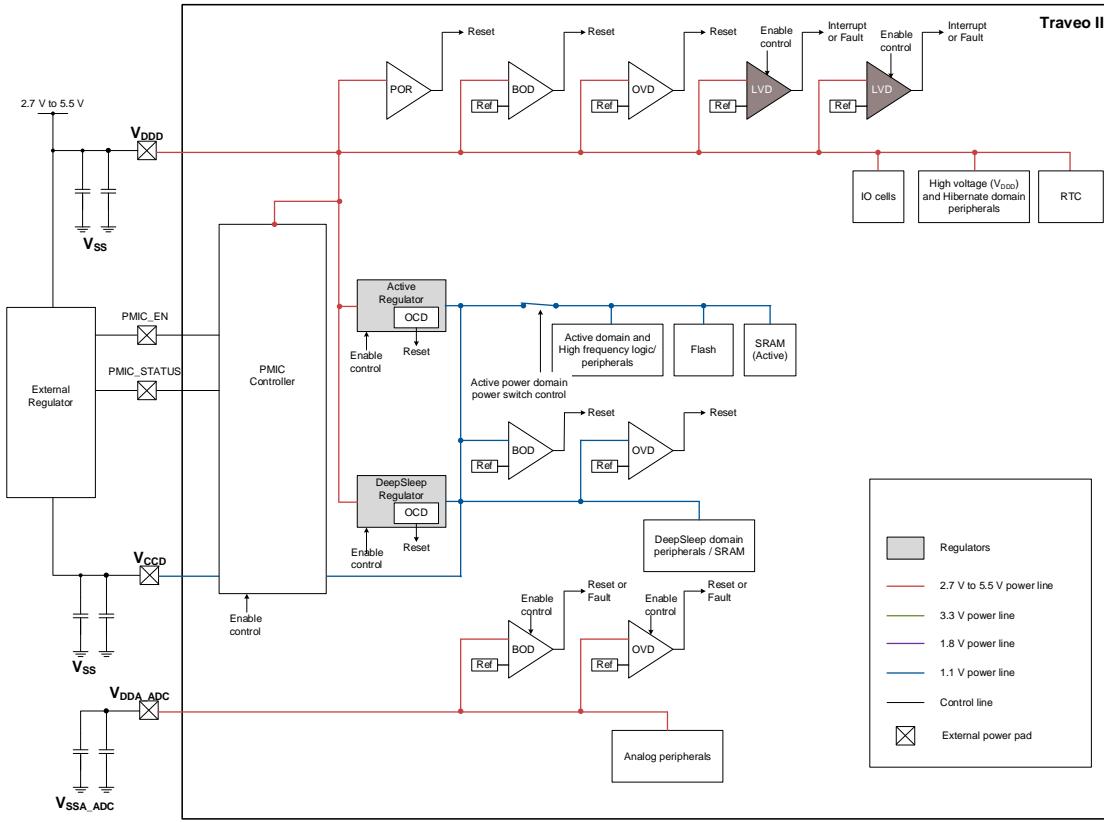
Review datasheet and TRM section 16.3.2 for additional details



¹ If V_{DDD}/V_{DDA_ADC} falls below 2.7 V (minimum V_{DDD}/V_{DDA_ADC}), the device will operate out of specification. To prevent that, use the 3.0-V trip point

² Even if V_{DDA_ADC} is low, the MCU can boot because it does not generate a reset as default

Low-Voltage Detection (LVD) Block Diagram

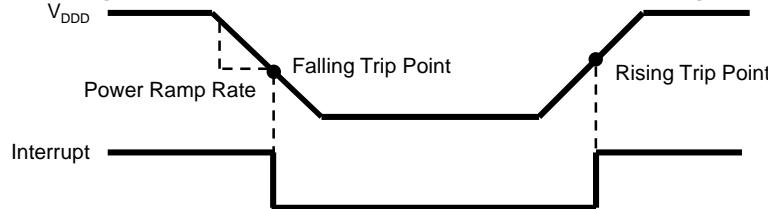


Hint Bar

Review datasheet and TRM section 16.3 for additional details

LVD Features

- › Detects the warning voltage level to take preventive measures in the system
- › Can be enabled or disabled (default) by software, except in Hibernate and XRES modes
 - LVD on V_{DDD}
 - Generates an interrupt or a fault if a voltage level meets the trip point
 - An interrupt or a fault and trip point are configurable by software
 - Supports up to 26 trip points to monitor between 2.8 V and 5.3 V (0.1-V step)
 - Can be configured as falling (low voltage), rising (high voltage) detection, or both
- › Use case for two LVD units
 - LVD1: Use the falling trip point (3.5 V) to detect the low-voltage warning
 - LVD2: Use the rising trip (5.3 V) to detect the over-voltage warning

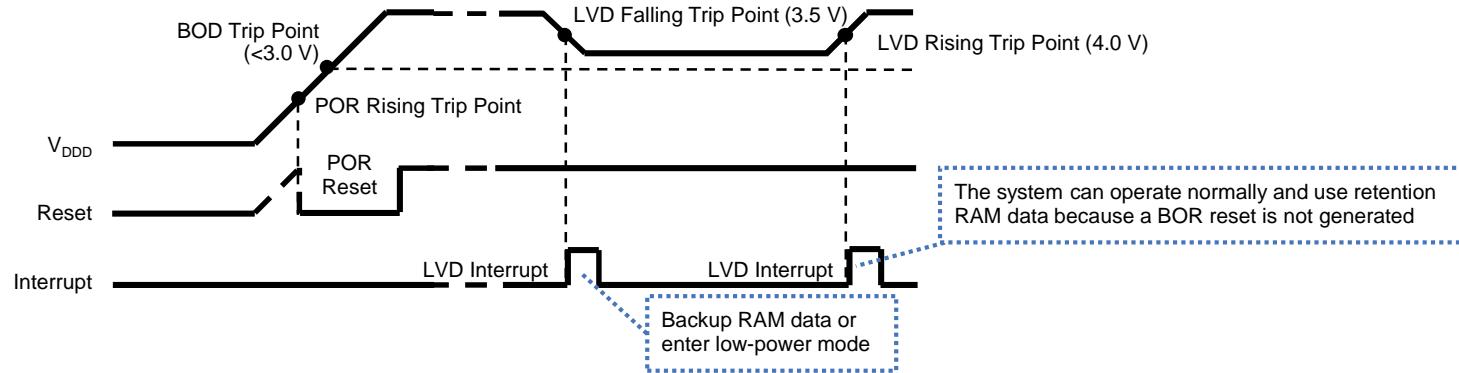


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Review datasheet and TRM section 16.3.4 for additional details

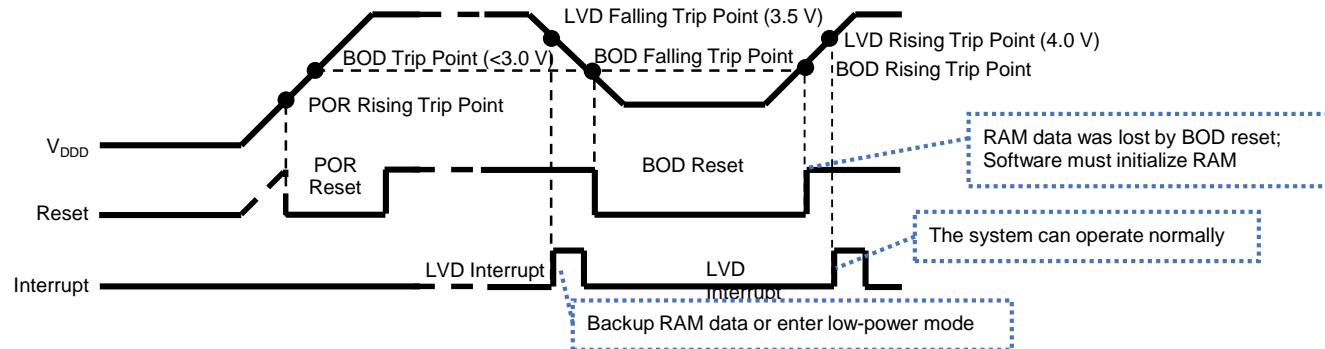
POR, BOD, and LVD Use Cases (1/2)

- › Purpose: Judge whether RAM contents have been retained by using voltage monitoring
- › Setting and condition
 - MCU operation conditions
 - LVD trip point can be in MCU operation range – RAM retention
 - LVD falling trip point (3.5 V): Warning LVD for safety system operation
 - LVD rising trip point (4.0 V): User program restart trigger
 - BOD reset (<3.0 V) is an asynchronous reset – No RAM retention
- › Use Case: For RAM, contents are retained (no BOD reset generation)



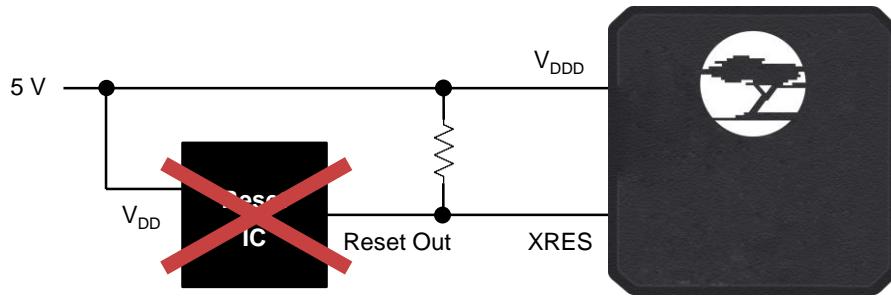
POR, BOD, and LVD Use Cases (2/2)

- › Purpose: Judge whether RAM contents have been retained by using voltage monitoring
- › Setting and condition
 - MCU operation conditions:
 - LVD trip point can be in MCU operation range – RAM retention
 - LVD falling trip point (3.5 V): Warning LVD for safety system operation
 - LVD rising trip point (4.0 V): User program restart trigger
 - BOD reset (<3.0 V) is an asynchronous reset – No RAM retention
- › Use Case: For RAM, contents have not been retained (BOD reset generation)



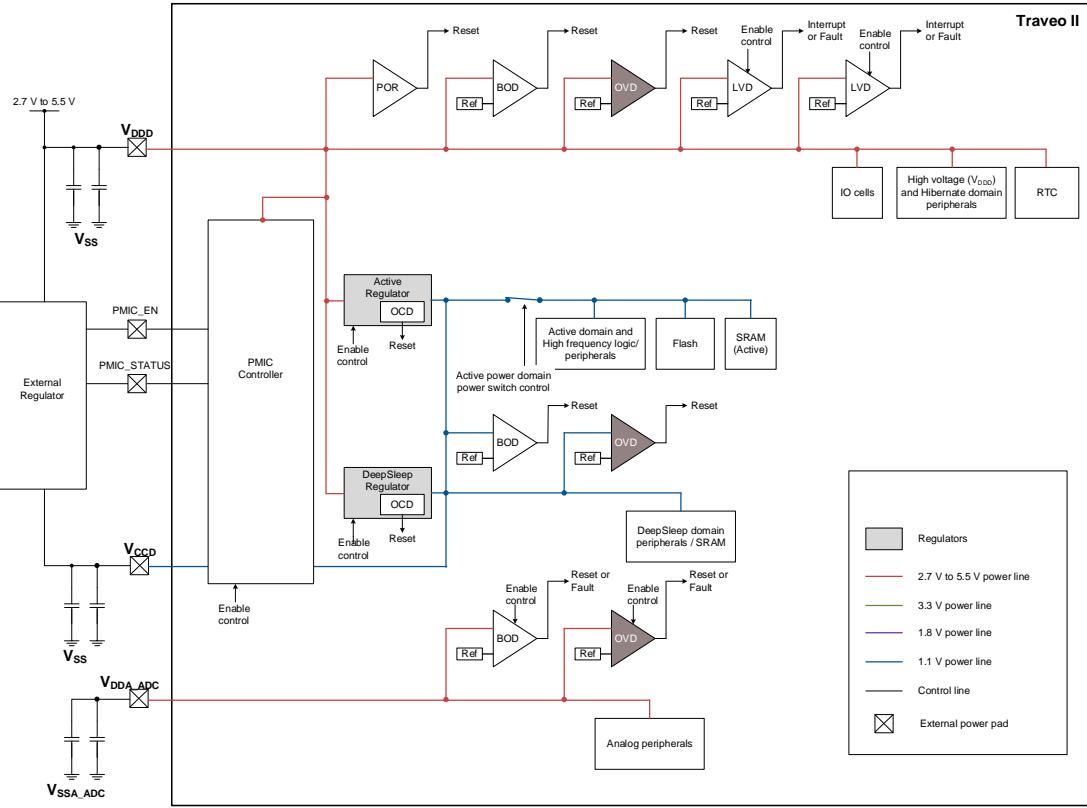
POR, BOD, and LVD Advantage

- › Reduced BOM costs for low-cost applications using internal POR, BOD, and LVD¹



¹ Review TRM and datasheet to confirm if the POR, BOD, and LVD specifications meet the safety requirements of the system

Overvoltage Detection (OVD) Block Diagram



Hint Bar

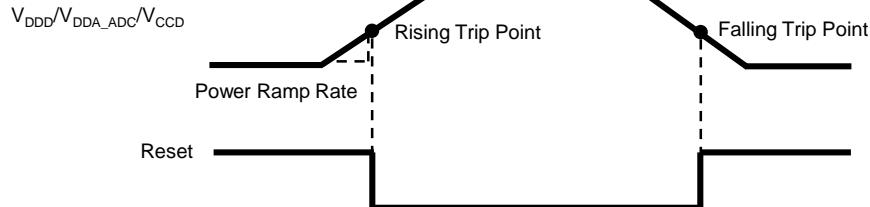
Review datasheet and TRM section 16.3 for additional details

OVD Features

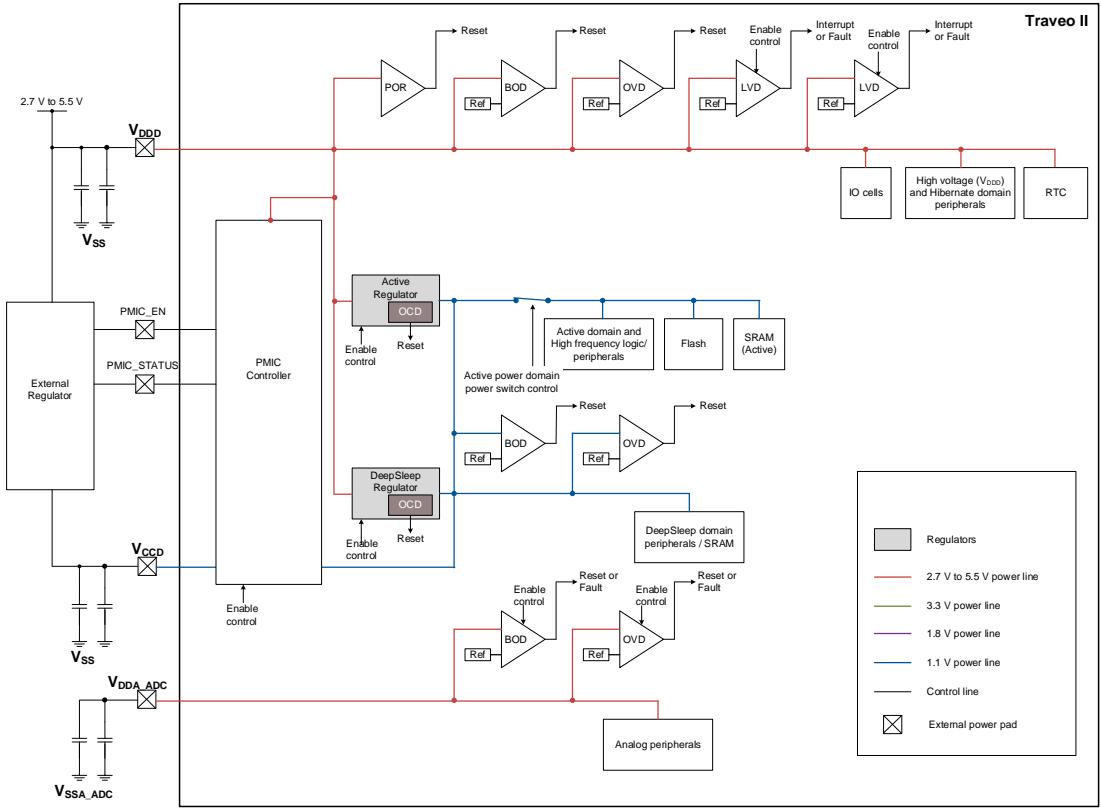
- › Detects supply conditions above a threshold and applies a reset to the device
- › Always on except in Hibernate and XRES modes
 - OVD on V_{DDD}
 - Generates a reset if a voltage excursion dips above the rising trip point
 - Supports two trip points: > 5.5 V (default) or > 5.0 V
 - OVD on V_{DDA_ADC}
 - Generates a reset, a fault, or no action (default) if a voltage excursion dips above the rising trip point
 - Supports two trip points: > 5.5 V (default) or > 5.0 V
 - OVD on V_{CCD}
 - Generates a reset if a voltage excursion dips above the rising trip point

Hint Bar

Review datasheet and TRM section 16.3.3 for additional details

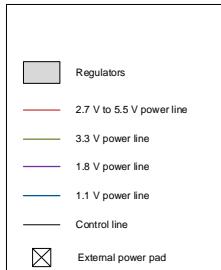


Over-Current Detection (OCD) Block Diagram



Hint Bar

Review datasheet and TRM section 16.3 for additional details



OCD Features

- › Detects if the device current is over the regulator limit
- › Always on except in Hibernate and XRES modes
 - OCD on V_{CCD}
 - Generates a reset by detecting if the load current of a regulator is higher than expected
 - OCD is not available when using PMIC

Hint Bar

Review datasheet and TRM section 16.3.5 for additional details

Summary of Voltage Monitoring

| Monitored Supply | Monitor | Trip Point | Output | Available Power Mode |
|------------------|------------------|-------------------|--------------------------------|---|
| V_{DDD} | POR | 1 (Fixed) | Reset | All power modes |
| | BOD | 2 (Programmable) | Reset | All power modes except Hibernate and XRES modes |
| | OVD | 2 (Programmable) | Reset | |
| | LVD | 26 (Programmable) | Interrupt, Fault, or No action | |
| V_{DDA_ADC} | BOD | 2 (Programmable) | Reset, Fault, or No action | |
| | OVD | 2 (Programmable) | Reset, Fault, or No action | |
| V_{CCD} | BOD | 1 (Fixed) | Reset | |
| | OVD | 1 (Fixed) | Reset | |
| | OCD ¹ | 1 (Fixed) | Reset | |

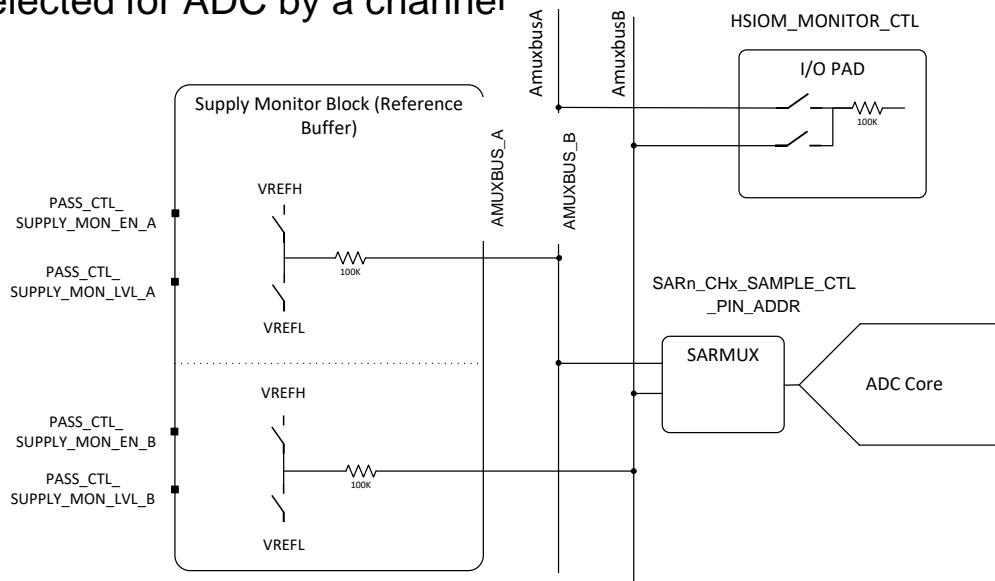
¹ Traveo II does not have the OCD for the PMIC.

Voltage Monitoring by ADC

- › ADC is used for all other power supplies
- › A monitor switch is provided between power/ground pad and AMUXBUS_A/B by the HSIOM_MONITOR_CTL register
- › Midpoint of the signal (AMUXBUS_A/B) is connected to the SARMUX (internal signals) and can be selected for ADC by a channel
- › Use case
 - V_{DDIO} monitoring

Hint Bar

Review TRM section 16.3.7
for additional details



Power Supply Monitoring by ADC

- Relation between HSIOM_MONITOR_CTL_0 Register and Power/Ground Pins

| HSIOM_MONITOR_CTL_0 | Power/Ground Pads | AMUXBUS | CYT4DN Pin No. of Package | | Hint Bar |
|---------------------|-------------------|---------|---|--|---|
| | | | BGA-500 | BGA-327 | |
| Bit 0 | V _{DDD} | A | G14, H20, J19, J20, K20, L20, M7, M20, N7, P7, P20, R20, T20, Y13, Y14, Y15 | F10, K15, R11, M6 | Review TRM sections 16.3.6 and 37.10 for additional details |
| Bit 2 | | | | | |
| Bit 22 | | | | | |
| Bit 1 | | | A3, A24, B2, B3, B24, B25, C1, C2, C3, C8, C14, C21, C24, C25, C26, D3, D8, D14, D21, E4, F4, F25, G4, H3, H4, H25, H26, J1, J2, J3, J4, K3, K4, K10, K11, K12, K13, K14, K15, K25, K26, L4, L10, L11, L12, L13, L14, L15, L16, L17, M4, M10, M11, M12, M13, M14, M15, M16, M17, N4, N10, N11, N12, N13, N14, N15, N16, N17, P3, P4, P10, P11, P12, P13, P14, P15, P16, P17, R1, R2, R3, R4, R10, R11, R12, R13, R14, R15, R16, T4, T10, T11, T12, T13, T14, T15, T16, U4, U10, U11, U12, U13, U14, V3, V4, W3, W4, Y3, Y4, AA3, AA4, AB3, AB4, AC3, AC8, AC13, AD1, AD2, AD3, AD8, AD13, AD18, AE2, AE3, AF3, R17, T17, K17, K16 | | |
| Bit 3 | | | | | |
| Bit 6 | | | | | |
| Bit 8 | | | | | |
| Bit 10 | | | | | |
| Bit 12 | | | | | |
| Bit 21 | V _{SS} | B | | A1, A20, H13, E20, F19, G20, H9, H10, H11, H12, J8, J9, J10, J11, J12, J13, H4, K8, K9, K10, K11, K12, K13, L8, L9, L10, L11, L12, L13, N1, M8, M9, M10, M11, M12, M13, N8, N9, N10, N11, N12, N13, Y1 | |

Power Supply Monitoring by ADC

- Relation between HSIOM_MONITOR_CTL_0 Register and Power/Ground Pins

| HSIOM_MONITOR_CTL_0 | Power/Ground Pads | AMUXBUS | CYT4DN Pin No. of Package | |
|---------------------|---------------------------|---------|---|--------------------|
| | | | BGA-500 | BGA-327 |
| Bit 4 | V _{DDIO_SMIF} | A | H8, H9, J8, K8, L8, M8 | J6, G6, H6 |
| Bit 5 | V _{DDIO_SMIF_HV} | A | G7, G8, H7, J7, K7, L7 | L6, K6 |
| Bit 7 | V _{DDIO_HSIO} | A | R7, T7, U7, V7, W7, Y7, Y8, Y9, Y10, Y11, Y12 | N6, R7, R8, R9, R6 |
| Bit 9 | V _{DDIO_SMC} | A | G9, G10, G11, G12, G13 | F7, F8, F6 |
| Bit 11 | V _{DDIO_GPIO_0} | A | G19, G20 | F15 |
| Bit 13 | V _{DDA_DAC} | A | N19, N20, P19 | J15 |
| Bit 14 | V _{SSA_DAC} | B | G23, G24, H24, J24, K24, L24, M24, M23 | G17, G18 |
| Bit 15 | V _{DDA_ADC} | A | H17 | F12 |
| Bit 16 | V _{SSA_ADC} | B | H16 | D12 |
| Bit 17 | V _{REFH} | A | H18 | F13 |
| Bit 18 | V _{REFL} | B | G16 | D13 |
| Bit 19 | V _{DDIO_GPIO_1} | A | G17, G18, H19 | F14 |
| Bit 20 | V _{DDIO_GPIO_2} | A | G15, H15 | F11 |

Hint Bar

Review TRM sections 16.3.6 and 30.10 for additional details

Power Supply Monitoring by ADC

- Relation between HSIOM_MONITOR_CTL_0 Register and Power/Ground Pins

| HSIOM_MONITOR_CTL_0 | Power/Ground Pads | AMUXBUS | CYT3DL Pin No. of Package | | |
|---------------------|--------------------------|---------|---|------------------------------|------------------------------|
| | | | BGA-272 | TEQFP-216 | TEQFP-208 |
| Bit 0 | V _{DDD} | A | M7, N7, G12, G13, F9 | 140 | 136 |
| Bit 2 | | | | | |
| Bit 1 | V _{SSD} | B | A2, B3, C4, D4, F3, F4, K1, K2, K3, K4, R3, R4, T1, V1, R10, U10, H17, H18, F17, F18, A18, B17, A10, H8, H9, H10, H11, J8, J9, J10, J11, K8, K9, K10, K11, L8, L9, L10, L11 | 142 (V _{SSD}) | 138 (V _{SSD}) |
| Bit 3 | | | | - | - |
| Bit 5 | | | | 40 (V _{SSIO_HSI0}) | 38 (V _{SSIO_HSI0}) |
| Bit 7 | | | | 194 (V _{SSIO_SMC}) | 186 (V _{SSIO_SMC}) |
| Bit 9 | | | | 180 (V _{SSD}) | 172 (V _{SSD}) |
| Bit 4 | V _{DDIO_HSI0} | A | G4, J4, H6, J6, K6, L6, M6, N6 | 41 | 39 |
| Bit 6 | V _{DDIO_SMC} | A | F7, G6, G7 | 195 | 187 |
| Bit 8 | V _{DDIO_GPIO_1} | A | F10, F13 | 149 | 143 |
| Bit 10 | V _{SSA_DAC} | A | G15, G16 | 135 | 131 |
| Bit 11 | V _{DDA_DAC} | A | H13 | 132 | 128 |
| Bit 12 | V _{DDA_ADC} | A | F11 | 160 | 154 |

Hint Bar

Review TRM sections 16.3.6 and 37.10 for additional details

Power Supply Monitoring by ADC

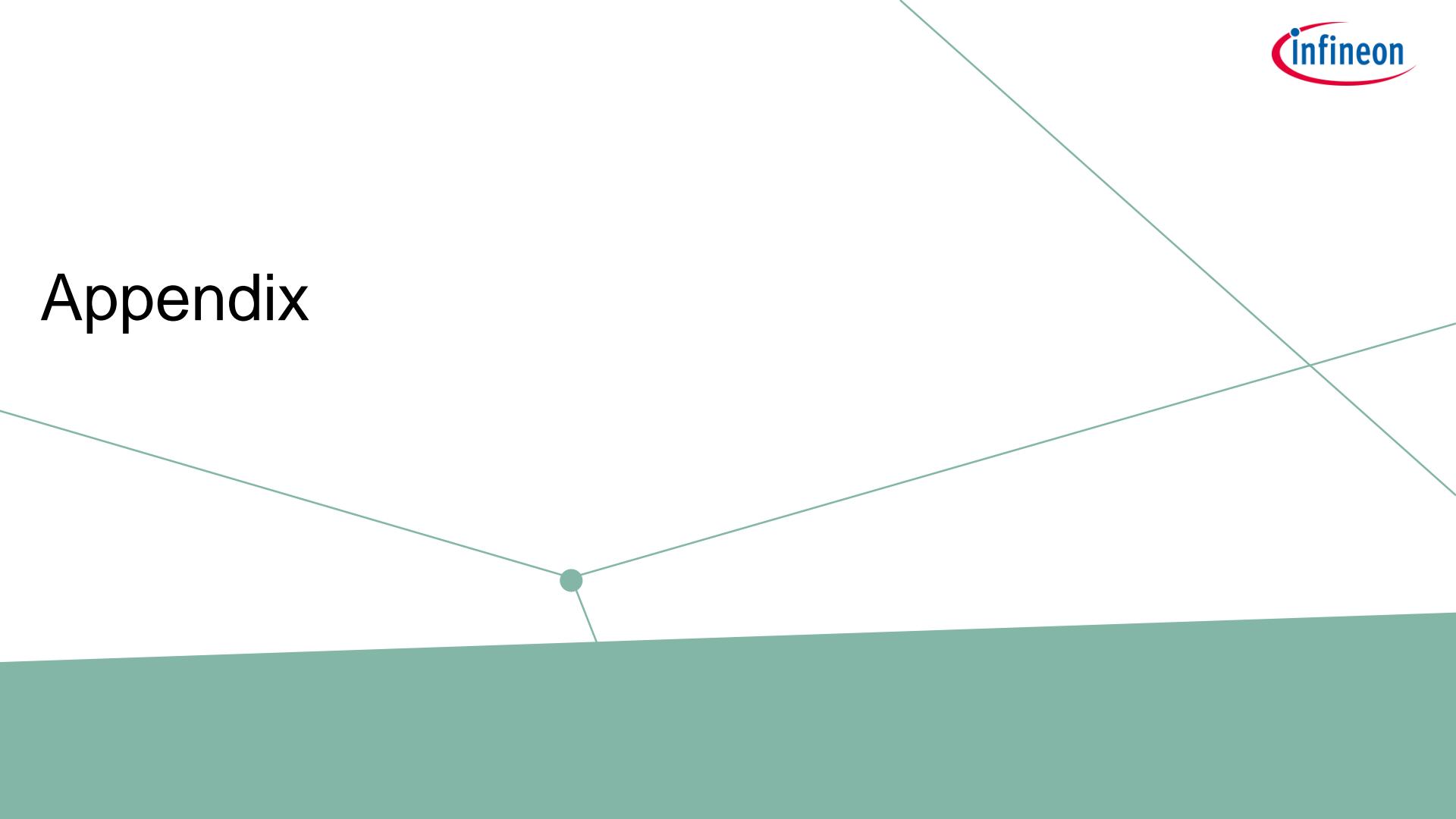
- Relation between HSIOM_MONITOR_CTL_0 Register and Power/Ground Pins

| HSIOM_MONITOR_CTL_0 | Power/Ground Pads | AMUXBUS | CYT3DL Pin No. of Package | | |
|---------------------|--------------------------|---------|---------------------------|-----------------------------|-----------------------------|
| | | | BGA-272 | TEQFP-216 | TEQFP-208 |
| Bit 13 | V _{SSA_ADC} | B | D11 | 161 | 155 |
| Bit 14 | V _{REFH} | A | F12 | 159 | 153 |
| Bit 15 | V _{REFL} | B | D12 | 161 (V _{SSA_ADC}) | 155 (V _{SSA_ADC}) |
| Bit 16 | V _{DDIO_GPIO_2} | A | F8 | 162 | 156 |

Hint Bar

Review TRM sections
16.3.6 and 30.10 for
additional details

Appendix



Comparison between CYT2B, CYT3B/4B, and CYT3D/4D

| Features | CYT2B | CYT3B/4B | CYT3D/4D |
|-----------------------------|---|--|---|
| Power Supply and Monitoring | Power supply $V_{DDD} = 2.7 \text{ V to } 5.5 \text{ V}$ | $V_{DDD} = 2.7 \text{ V to } 5.5 \text{ V (up to } 300 \text{ mA)}$ $V_{DDD} = 2.7 \text{ V to } 5.5 \text{ V and } V_{CCD} = 1.15 \text{ V (exceeds } 300 \text{ mA)}$ | |
| | 5.0 V I/O power supply | V_{DDIO_1}, V_{DDIO_2} | $V_{DDIO_GPIO}, V_{DDIO_SMC}$ |
| | 3.3 V I/O power supply | N/A | $V_{DDIO_HSIO}, V_{DDIO_SMIF_HV}$ |
| | 1.8 V I/O power supply | N/A | V_{DDIO_SMIF} |
| | Analog power supply | V_{DDA} | $V_{DDA_ADC}, V_{DDA_DAC}, V_{DDA_MIPI}, V_{DDA_FPD0}, V_{DDA_FPD1}, V_{DDHA_FPD0}, V_{DDHA_FPD1}, V_{DDPLL_FPD0}, V_{DDPLL_FPD1}$ |
| | Active/DeepSleep regulator | | Same |
| | External transistor control | N/A | Available |
| | External PMIC control | N/A | Available |
| | POR/BOD/OVD/LVD | | Same |



Part of your life. Part of tomorrow.

Revision History

| Revision | ECN | Submission Data | Description of Change |
|----------|---------|-----------------|--|
| ** | 6629932 | 07/19/2019 | Initial release |
| *A | 7053309 | 12/16/2020 | Update page 2, 4 to 11, 13 to 15, 20 to 22, 26, 27, 31. Add page 28, 29 |